



COPY OF PAPERS
ORIGINALS FILED

Attorney's Docket No.: 07043-060002 / B97-065-2

RECEIVED

SEP 10 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Timothy J. Brosnihan et al
Serial No. : 09/342,348
Filed : June 29, 1999
Title : METHOD OF FABRICATING A MICROFABRICATED HIGH ASPECT RATIO DEVICE WITH ELECTRICAL ISOLATION

Commissioner for Patents
Washington, D.C. 20231

#11/Anh C
Rm (NE)
9/12/02

AMENDMENT

In response to the action mailed March 28, 2002, please amend the subject application as follows:.

-- 1. (Twice amended) A method of fabricating a microelectromechanical system, comprising:

providing a substrate having a device layer;

etching a first trench in the device layer, the first trench surrounding a first region of the substrate;

depositing a dielectric isolation layer in the first trench to electrically isolate the first region from a second region of the substrate; and

etching a second trench in the device layer, the second trench located in the first region and defining a microstructure, and the first trench electrically isolating elements of the microstructure from each other. --

REMARKS

Claims 1, 2 and 5-11 stand rejected as anticipated by Bashir et al. (U.S. Patent No. 5,747,353). Claim 3 stands rejected as obvious over Bashir et al., and claims 4 and 12 stand rejected as obvious over Bashir et al. in view of Hunter et al. (U.S. Patent No. 4,631,803).

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

August 28, 2002
Date of Deposit

Signature

Judith Cotham
Typed or Printed Name of Person Signing Certificate